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Kind regards,

Team Nexperia

BC856BM

60 V, 100 mA PNP general-purpose transistor

19 August 2015 **Product data sheet**

1. General description

PNP general-purpose transistor in a leadless ultra small DFN1006-3 (SOT883) Surface-Mounted Device (SMD) plastic package.

NPN complement: BC846BM.

2. Features and benefits

- Leadless ultra small SMD plastic package
- Power dissipation comparable to SOT23
- AEC-Q101 qualified

3. Applications

- General-purpose switching and amplification
- Mobile applications

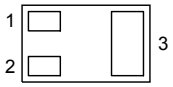
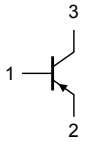
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base		-	-	-60	V
I_C	collector current			-	-	-100	mA
h_{FE}	DC current gain	V_{CE} = -5 V; I_C = -2 mA; T_{amb} = 25 °C		220	-	475	

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	B	base	 Transparent top view **DFN1006-3 (SOT883)**	 *sym013*
2	E	emitter		
3	C	collector		

Scan or click this QR code to view the latest information for this product

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BC856BM	DFN1006-3	DFN1006-3: leadless ultra small plastic package; 3 solder lands	SOT883

7. Marking

Table 4. Marking codes

Type number	Marking code
BC856BM	J2

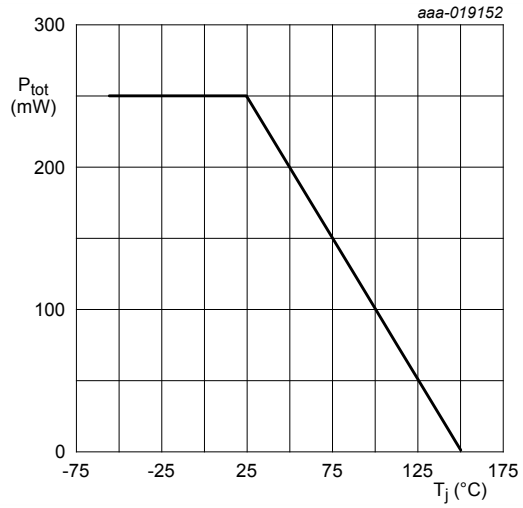
8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter		-	-80	V
V_{CEO}	collector-emitter voltage	open base		-	-60	V
V_{EBO}	emitter-base voltage	open collector		-	-6	V
I_C	collector current			-	-100	mA
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms		-	-200	mA
I_{BM}	peak base current			-	-200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1]	-	250	mW
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			-55	150	°C
T_{stg}	storage temperature			-65	150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.



FR4 PCB, standard footprint

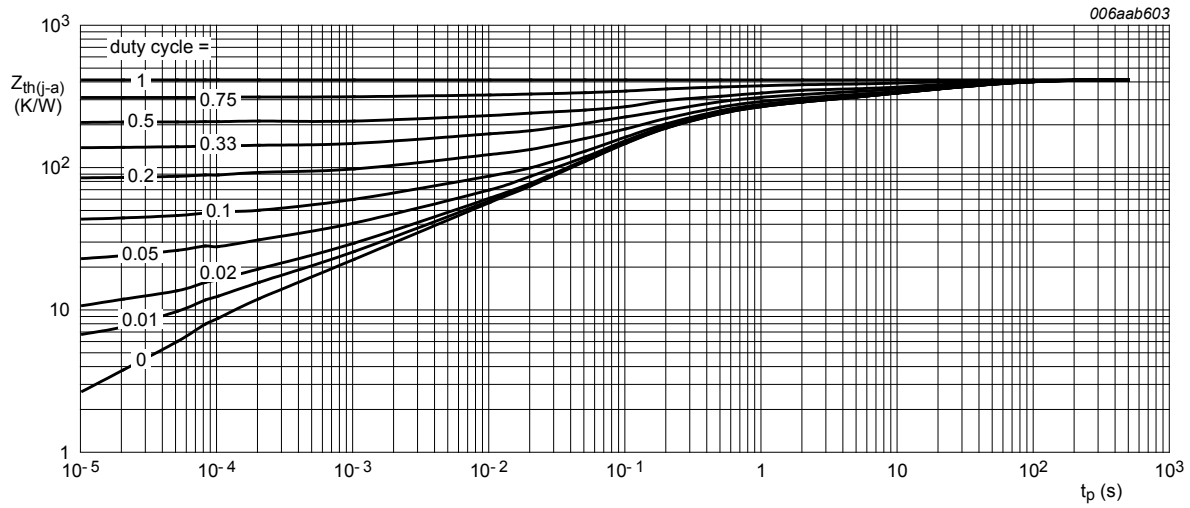
Fig. 1. Power derating curve DFN1006-3 (SOT883)

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	500	K/W

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.



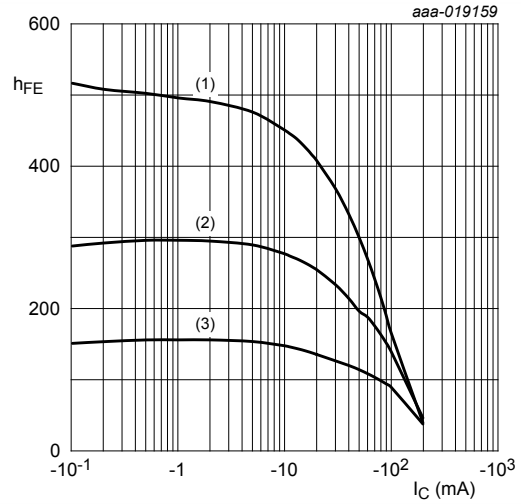
FR4 PCB, standard footprint

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	V_{CB} = -30 V; I_E = 0 A; T_{amb} = 25 °C		-	-	-15	nA
		V_{CB} = -30 V; I_E = 0 A; T_j = 150 °C		-	-	-5	µA
I_{EBO}	emitter-base cut-off current	V_{EB} = -5 V; I_C = 0 A; T_{amb} = 25 °C		-	-	-100	nA
h_{FE}	DC current gain	V_{CE} = -5 V; I_C = -2 mA; T_{amb} = 25 °C		220	-	475	
V_{CEsat}	collector-emitter saturation voltage	I_C = -10 mA; I_B = -0.5 mA; T_{amb} = 25 °C		-	-	-200	mV
		I_C = -100 mA; I_B = -5 mA; pulsed; $t_p \leq 300$ µs; $\delta \leq 0.02$; T_{amb} = 25 °C		-	-	-400	mV
V_{BEsat}	base-emitter saturation voltage	I_C = -10 mA; I_B = -0.5 mA; T_{amb} = 25 °C		-	-700	-	mV
		I_C = -100 mA; I_B = -5 mA; T_{amb} = 25 °C		-	-850	-	mV
V_{BE}	base-emitter voltage	V_{CE} = -5 V; I_C = -2 mA; T_{amb} = 25 °C		-600	-	-750	mV
		V_{CE} = -5 V; I_C = -10 mA; T_{amb} = 25 °C		-	-	-820	mV
C_C	collector capacitance	V_{CB} = -10 V; I_E = 0 A; i_e = 0 A; f = 1 MHz; T_{amb} = 25 °C		-	-	2.5	pF
C_E	emitter capacitance	V_{EB} = -0.5 V; I_C = 0 A; i_c = 0 A; f = 1 MHz; T_{amb} = 25 °C		-	4.5	-	pF
f_T	transition frequency	V_{CE} = -5 V; I_C = -10 mA; f = 100 MHz; T_{amb} = 25 °C		100	-	-	MHz
NF	noise figure	V_{CE} = -5 V; I_C = -200 µA; R_S = 2 kΩ; f = 1 kHz; B = 200 Hz; T_{amb} = 25 °C		-	-	10	dB



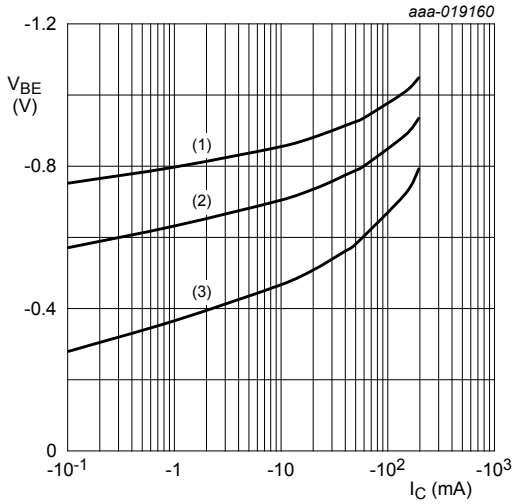
V_{CE} = -5 V

(1) T_{amb} = 150 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = −55 °C

Fig. 3. DC current gain as a function of collector current; typical values



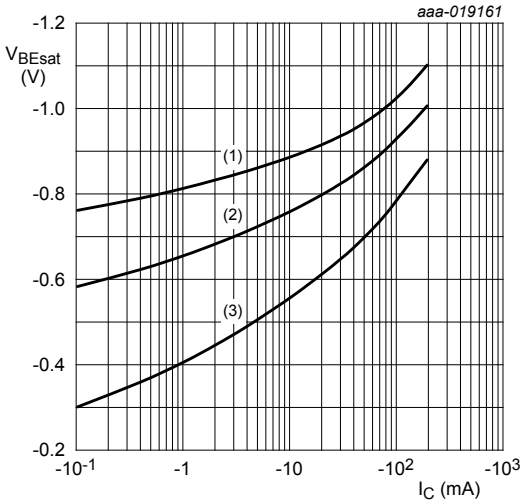
V_{CE} = -5 V

(1) T_{amb} = -55 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = 150 °C

Fig. 4. Base-emitter voltage as a function of collector current; typical values



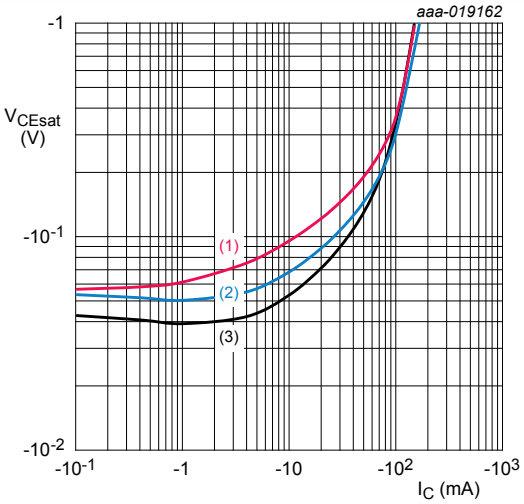
I_C/I_B = 20

(1) T_{amb} = -55 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = 150°C

Fig. 5. Base-emitter saturation voltage as a function of collector current; typical values



I_C/I_B = 20

(1) T_{amb} = 150 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = -55 °C

Fig. 6. Collector-emitter saturation voltage as a function of collector current; typical values

11. Test information

11.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

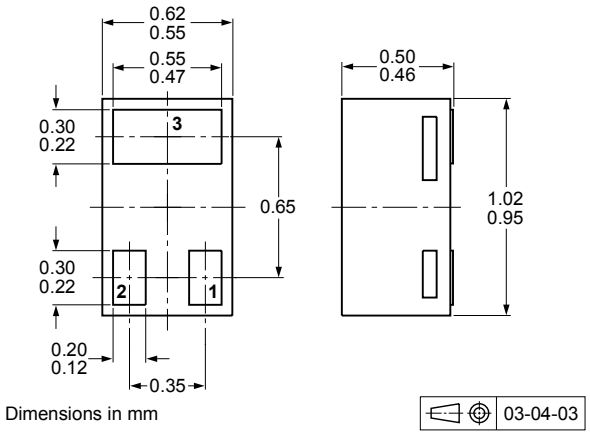


Fig. 7. Package outline DFN1006-3 (SOT883)

13. Soldering

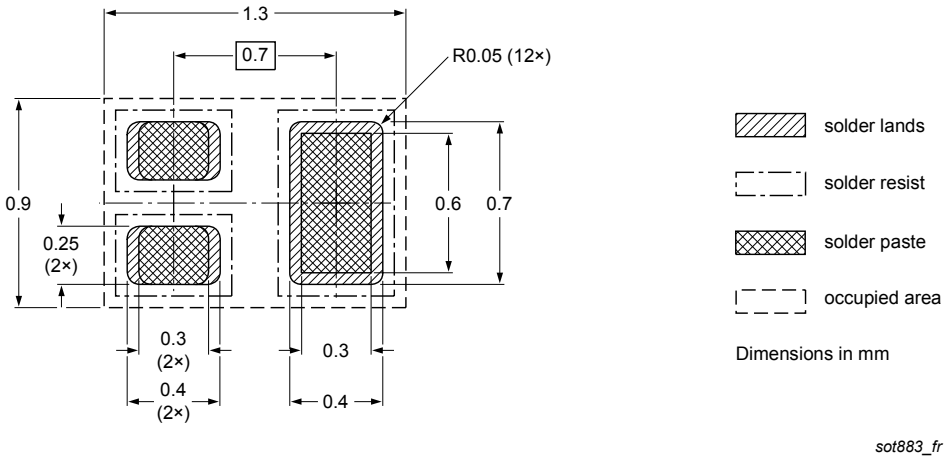


Fig. 8. Reflow soldering footprint for DFN1006-3 (SOT883)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
BC856BM v.1	20150819	Product data sheet	-	-

15. Legal information

15.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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